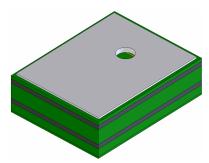
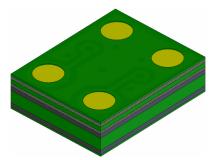




#### "Ultra-Mini" SiSonic<sup>™</sup> Microphone Specification With RF Protection





# Knowles Acoustics 1151 Maplewood Drive Itasca, IL 60143



Knowles Acoustics, a division of Knowles Electronics, LLC. Revision: C 1 of 10

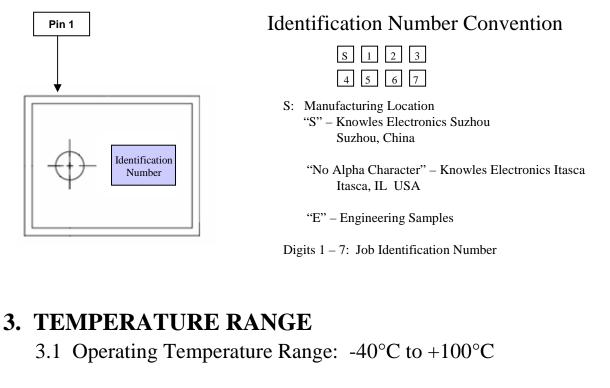




# **1. DESCRIPTION AND APPLICATION**

- 1.1 Description "Mini" Surface Mount Silicon Microphone with RF Filter Protection
- 1.2 Application Hand held consumer electronics

## 2. PART MARKING



3.2 Storage Temperature Range:  $-40^{\circ}$ C to  $+100^{\circ}$ C

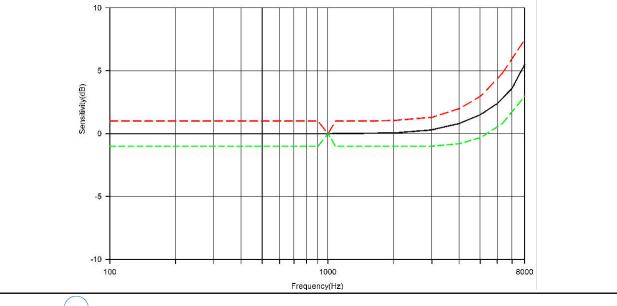




# 4. ACOUSTIC & ELECTRICAL SPECIFICATIONS

	Symbol	Condition			Unit	
	Symbol		Min.	Nom.	Max.	onit
Directivity		Omni-directional				
Sensitivity	S	@ 1kHz (0dB=1V/Pa)	-45	-42	-39	dB
Output impedance	Z <sub>OUT</sub>	@ 1kHz (0dB=1V/Pa)	n/a	n/a	300	Ω
Current Consumption	I <sub>DSS</sub>	across 1.5 to 3.6 volts	0.100	n/a	0.250	mA
Signal to Noise Ratio	S/N	@ 1kHz (0dB=1V/Pa)	55	59	n/a	dB
Supply Voltage	Vs		1.5	n/a	3.6	V
Typical Input Referred Noise	ENL	A-weighted	n/a	35	n/a	dBA SPL
Sensitivity Loss across Voltage		Change in sensitivity over 3.6v to 1.5v	No Change Across Voltage Range		dB	
Maximum Input Sound Level			PL, THD < 1% L, THD = < 10%			dB



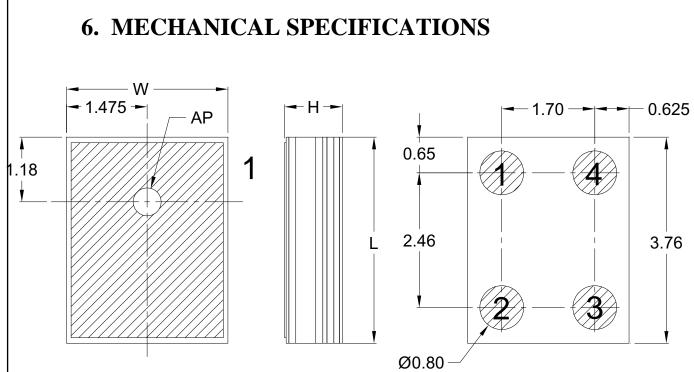




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Revision: C 3 of 10





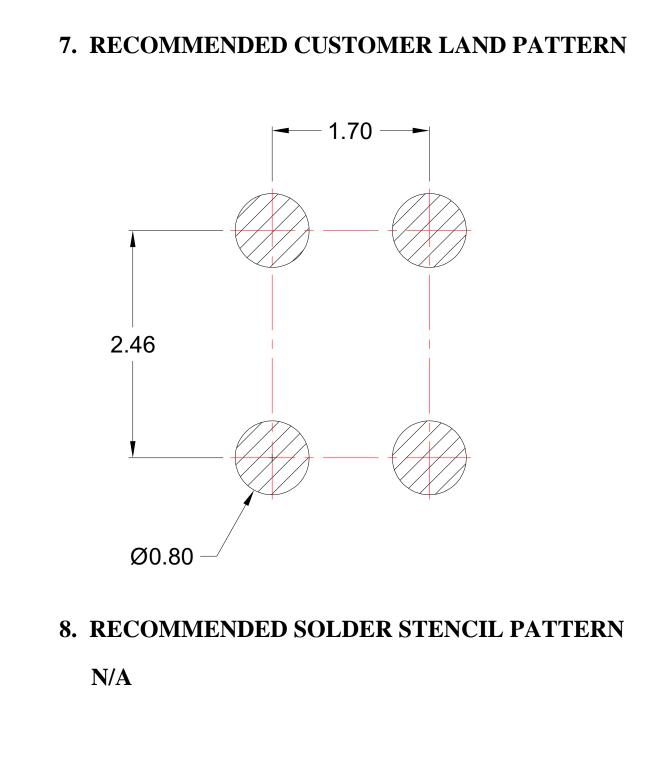
<b>PIN Designation</b>			
Pin #	Function		
1	Power		
2	Ground		
3	Ground		
4	Output		

ltem	Dimension	Tolerance (+/-)	Units
Length (L)	3.76	0.10	mm
Width (W)	2.95	0.10	mm
Height (H)	1.10	0.10	mm
Acoustic Port <b>(Diameter)</b> (AP)	0.50	0.10	mm

Note: (Tolerance +/-0.15mm unless otherwise specified)



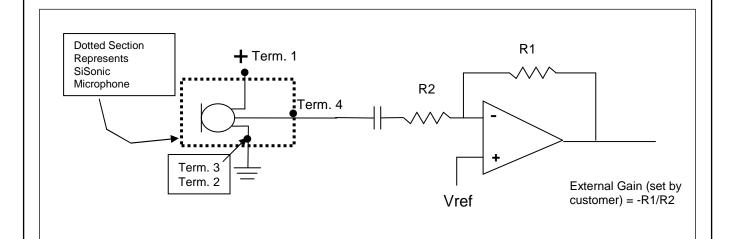






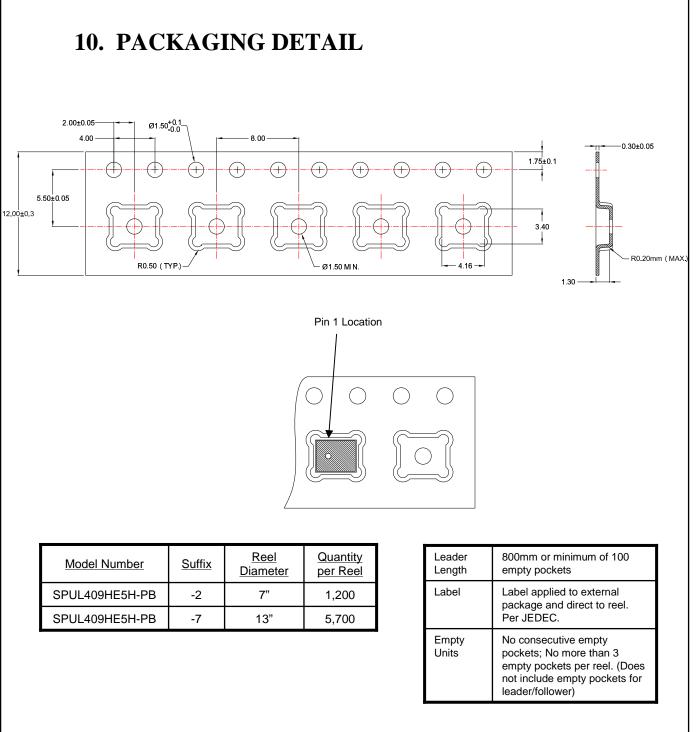


# 9. RECOMMENDED INTERFACE CIRCUIT





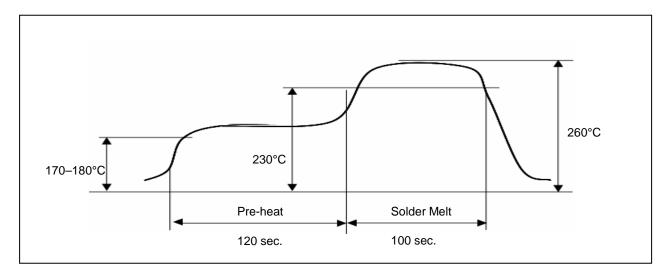








### **11. SOLDER REFLOW PROFILE**



<u>Stage</u>	<u>Temperature Profile</u>	<u>Time (maximum)</u>
Pre-heat	170 ~ 180 C	120 sec.
Solder Melt	Above 230 C	100 sec.
Peak	260 C maximum	30 sec.

#### Notes:

1.	Do not pull a vacuum over the port hole of the microphone. Pulling a
	vacuum over the port hole can damage the device.
2.	Do not board wash after the reflow process. Board washing and
	cleaning agents can damage the device. Do not expose to ultrasonic

- processing or cleaning.
- 3. Number of Reflow = recommend no more than 3 cycles.

### **12. ADDITIONAL NOTES**

- (A) Packaging (reference SiSonic\_Packaging\_Spec.pdf)
- (B) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- (C) Exposure: Devices should not be exposed to high humidity, high temperature environment. MSL (moisture sensitivity level) Class 2.
- (D) Out of bag: Maximum of 90 days out of ESD moisture sensitive bag, assuming maximum conditions of 30°C/70% R.H.





# **13. RELIABILITY SPECIFICATIONS**

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

Test	Description
Thermal Shock	100 cycles of air-air thermal shock from -40C to +125C with 15min soaks. (ICE 68-2-4)
High Temperature Storage	+105C environment for 1,000 hours. (IEC 68-2-2 Test Ba)
Low Temperature Storage	-40C environment for 1,000 hours. (IEC 68-2-2 Test Aa)
High Temperature Bias	+105C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Ba)
Low Temperature Bias	-40C environment while under bias for 1,000 hours. (IEC 68-2-2 Test Aa)
Temperature / Humidity Bias	+85C/85% RH environment while under bias for 500 hours. (JESD22-A101A-B)
Vibration	4 cycles lasting 12 minutes from 20 to 2,000Hz in X, Y, and Z direction with a peak acceleration of 20g. (MIL 883E, Method 2007.2, A)
Electrostatic Discharge	3 discharges at +/- 8kV direct contact to the lid when unit is grounded (IEC 1000-4-2) and 3 discharges at +/- 2kV direct contact to the I/O pins (MIL 883E, Method 3015.7)
Reflow	5 reflow cycles with peak temperature of 260C.
Mechanical Shock	3 pulses of 10,000g in the X, Y, and Z direction. (IEC 68-2-27, Test Ea)





# **14. SPECIFICATION REVISIONS**

Revision	Detailed Specification Changes	Date
А	Preliminary Specification Release	02-14-2008
В	Specification Release. Update Product Marking	04-25-2008
С	Update Product Marking	06-26-2008

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